

FUTURE PLANS AND [REDACTED]

FUTURE PLANS

Please see “Business — Our Development Strategies” in this document for detailed descriptions of our future plans.

[REDACTED]

We estimate that the [REDACTED] from the [REDACTED], assuming an [REDACTED] of HK\$[REDACTED] per H Share (being the mid-point of the [REDACTED] stated in this document), will be approximately HK\$[REDACTED] million, after deduction of [REDACTED] fees, commissions, and estimated expenses payable by us in connection with the [REDACTED], and assuming the [REDACTED] is not exercised.

We intend to use the [REDACTED] from the [REDACTED] for the following purposes and in the approximate amounts set forth below:

- Approximately [REDACTED]% or HK\$[REDACTED] million of the [REDACTED] will be used for the construction of a new production base at our new headquarters in Zhuhai which will replace our current production facilities and also host our office space. According to F&S, the size of global plasma processing equipment market is expected to grow from RMB347.9 billion in 2025 to RMB528.3 billion in 2030, at a CAGR of 8.7%. To address the increasing demand from downstream customers and leverage favorable industry trends, we will enhance our production capacity and use the new production base for manufacturing of plasma processing equipment PCB and semiconductor manufacturing, as well as other applications. We also plan to purchase advanced high-precision production equipment to continually enhance the precision and efficiency of our production and assembly processes.
- approximately [REDACTED]% or HK\$[REDACTED] million, will be used to invest in R&D of forward looking technologies. This includes investments in the following R&D projects:

	Projects	Applications
1	PECVD equipment development	PECVD equipment is capable of depositing multiple types of films at lower temperatures and is vital for applications such as insulating and passivation layers. It is primarily used for the deposition of passivation layers in semiconductor devices, anti-reflective coatings in photovoltaics, and encapsulation layers in flexible displays. Our research focuses on large-area uniformity control, plasma stability, and enhancing the density of low-temperature deposition.
2	Metal etching technology	Metal etching technology is designed to precisely etch various metals and metal compounds, and is crucial for creating interconnects and electrodes in semiconductor manufacturing. It is mainly used to form conductive lines, such as aluminum or copper, in the interconnection layer. Our research and development mainly focus on precisely removing the metal film in specific areas, while protecting the underlying structure and sidewalls to avoid short circuits or open circuits.

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	Projects	Applications
3	Polysilicon etching technology	Polysilicon etching is essential for forming transistor gates and capacitor electrodes. It is applied to define the core structure of transistors, the gate. The main challenge our research focuses on is the extremely high precision and size control required for polysilicon etching.

In particular, we plan to (i) enhance our R&D capabilities by constructing advanced R&D facilities at our new headquarters and upgrading our R&D and testing equipment, (ii) expand our R&D team and strengthen our innovation capabilities through the recruitment of talents and the implementation of systematic training programs, and (iii) procure raw materials and consumables for R&D and pilot production activities.

- approximately [REDACTED]% or HK\$[REDACTED] million, will be used for establishing offices overseas. We will mainly seek to expand our global presence by deploying sales and after-sale service team with the aim of enhancing our reach to local customers overseas and optimize our product customization to improve customer satisfaction and solidify our market presence.
- approximately [REDACTED]% or HK\$[REDACTED] million will be used for general corporate and working capital purposes.

The above allocation of the [REDACTED] will be adjusted on a pro rata basis in the event that the [REDACTED] is fixed at a higher or lower level compared to the mid-point of the estimated [REDACTED] or that the [REDACTED] is exercised.

If the [REDACTED] is fixed at HK\$[REDACTED] per H Share (being the high-end of the [REDACTED] stated in this document), and assuming the [REDACTED] is not exercised, we estimate that the [REDACTED] from the [REDACTED] will be approximately HK\$[REDACTED] million, after deduction of [REDACTED] fees, commissions, and estimated expenses payable by us in connection with the [REDACTED].

If the [REDACTED] is fixed at HK\$[REDACTED] per H Share (being the low-end of the [REDACTED] stated in this document), and assuming the [REDACTED] is not exercised, we estimate that the [REDACTED] from the [REDACTED] will be approximately HK\$[REDACTED] million, after deduction of [REDACTED] fees, commissions, and estimated expenses payable by us in connection with the [REDACTED].

If the [REDACTED] is exercised in full, the [REDACTED] that we will receive will be approximately HK\$[REDACTED] million, assuming an [REDACTED] of HK\$[REDACTED] per H Share (being the mid-point of the indicative [REDACTED]). In the event that the [REDACTED] is exercised in full, we intend to apply the additional [REDACTED] to the above purposes in the proportions stated above.

To the extent that the [REDACTED] from the [REDACTED] are not immediately applied to the above purposes and to the extent permitted by applicable law and regulations, we intend to deposit the [REDACTED] into short-term interest-bearing accounts at licensed commercial banks and/or other authorized financial institutions. We will make an appropriate announcement if there is any change to the above proposed [REDACTED].